

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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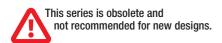






BOURNS®

- 5 A Continuous On-State Current
- 20 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 1 mA



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	TIC108D		400	
Repetitive peak off-state voltage (see Note 1)	TIC108M	14	600	V
	TIC108S	V_{DRM}	700	
	TIC108N		800	
Repetitive peak reverse voltage	TIC108D		400	
	TIC108M	V	600	V
	TIC108S	V _{RRM}	700	
	TIC108N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)		I _{T(RMS)}	5	Α
Average on-state current (180° conduction angle) at (or below) 80°C case temperature		1	3.2	Α
(see Note 3)		I _{T(AV)}	3.2	^
Surge on-state current (see Note 4)			20	Α
Peak positive gate current (pulse width ≤ 300 µs)		I _{GM}	0.2	Α
Peak gate power dissipation (pulse width ≤ 300 µs)		P _{GM}	1.3	W
Average gate power dissipation (see Note 5)		$P_{G(AV)}$	0.3	W
Operating case temperature range			-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds		T _L	230	°C

- NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 $k\Omega$.
 - 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
 - 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
 - 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 5. This value applies for a maximum averaging time of 20 ms.



electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}	R _{GK} = 1 kΩ	T _C = 110°C			400	μА
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			1	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs	0.2	0.5	1	mA
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = - 40°C			1.2	
V _{GT} Gate	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$		0.4	0.6	1	٧
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	T _C = 110°C	0.2			
I _H	Holding current	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 20 \text{ mA}$	$R_{GK} = 1 k\Omega$	T _C = - 40°C		3.5	15	mA
Н ПС	Tiolaing current	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 20 \text{ mA}$	$R_{GK} = 1 k\Omega$			2	10	
V _T	On-state voltage	I _T = 5 A	(see Note 6)			1.3	1.7	V
dv/dt	Critical rate of rise of off-state voltage	V _D = rated V _D	R _{GK} = 1 kΩ	T _C = 110°C		20		V/µs

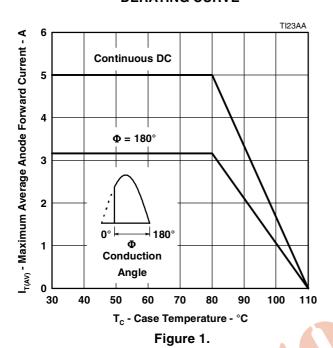
NOTE 6: This parameter must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

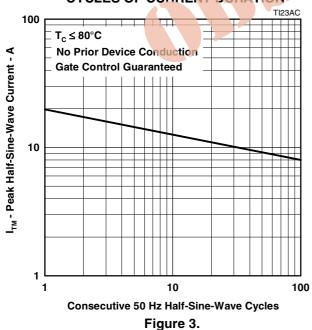
PARAMETER	MIN	TYP	MAX	UNIT
R _{0JC} Junction to case thermal resistance			3.5	°C/W
R _{eJA} Junction to free air thermal resistance			62.5	°C/W

THERMAL INFORMATION

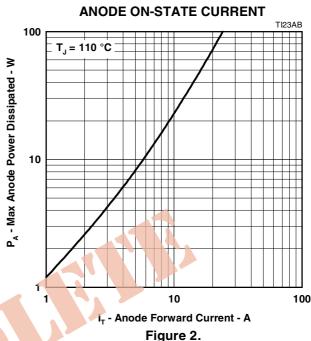
AVERAGE ANODE ON-STATE CURRENT DERATING CURVE



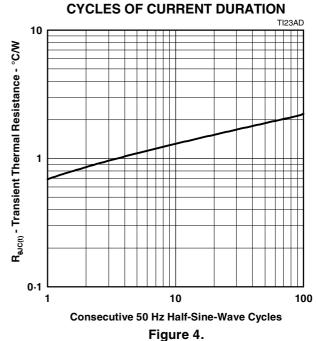
SURGE ON-STATE CURRENT vs CYCLES OF CURRENT DURATION



MAX ANODE POWER DISSIPATED vs



TRANSIENT THERMAL RESISTANCE vs

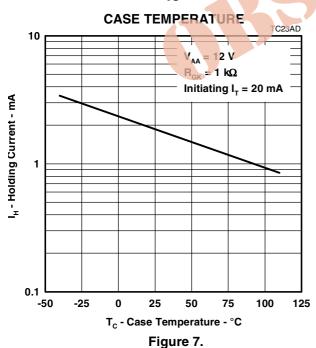


TYPICAL CHARACTERISTICS

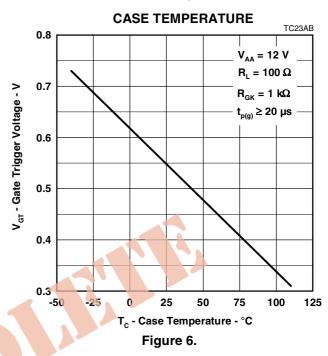
GATE TRIGGER CURRENT vs

CASE TEMPERATURE TC23AA 10 $V_{AA} = 12 V$ $R_1 = 100 \Omega$ _{G⊤} - Gate Trigger Current - mA $t_{p(q)} \ge 20 \mu s$ 0.1 -60 -20 40 60 80 100 120 -40 0 20 T_c - Case Temperature - °C Figure 5.

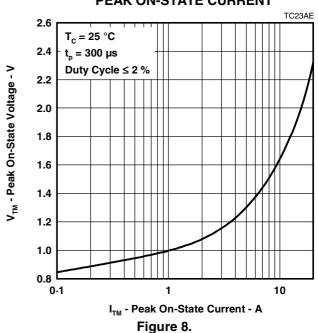
HOLDING CURRENT vs



GATE TRIGGER VOLTAGE vs



PEAK ON-STATE VOLTAGE vs PEAK ON-STATE CURRENT



PRODUCT INFORMATION